

SOT1145-1

plastic thin fine-pitch ball grid array package; 385 balls, 0.5 mm pitch, 12 mm x 12 mm x 0.81 mm body

19 August 2021

Package information

1 Package summary

Terminal position code B (bottom)

Package type descriptive code TFBGA385

Package type industry code TFBGA385

Package style descriptive code TFBGA (thin fine-pitch ball grid array)

Package body material type P (plastic)

Mounting method type S (surface mount)

Issue date18-08-2009Manufacturer package codeSOT1145

Table 1. Package summary

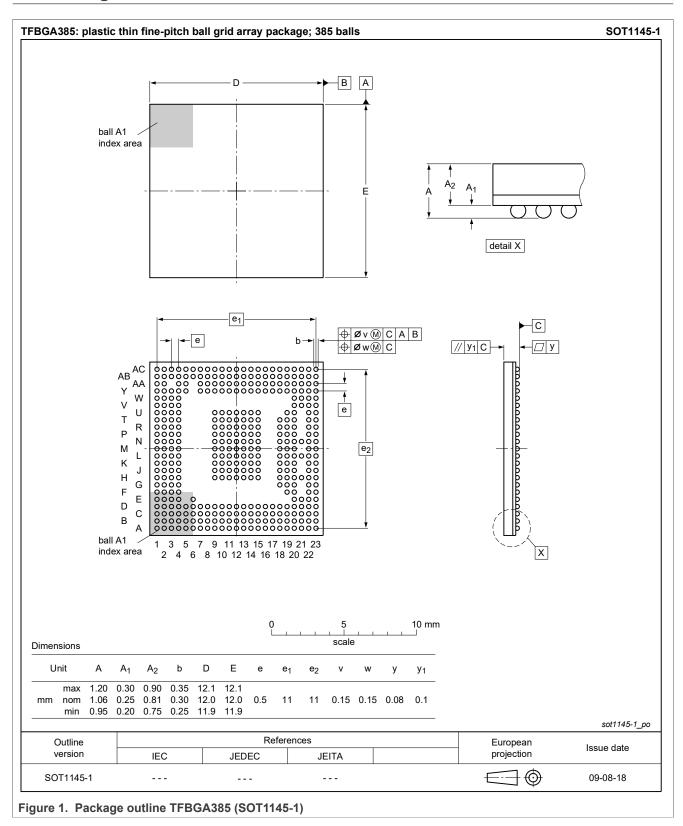
Parameter	Min	Nom	Max	Unit
package length	11.9	12	12.1	mm
package width	11.9	12	12.1	mm
seated height	0.95	1.06	1.2	mm
package height	0.75	0.81	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	385	-	



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2 Package outline



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3 Legal information

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